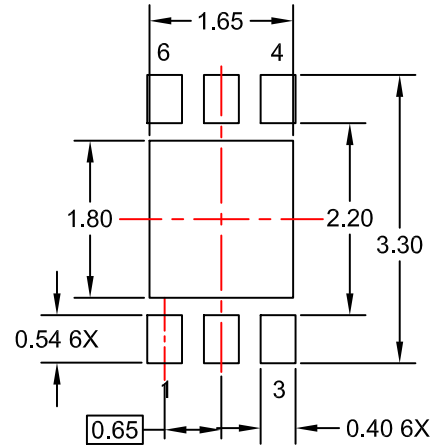
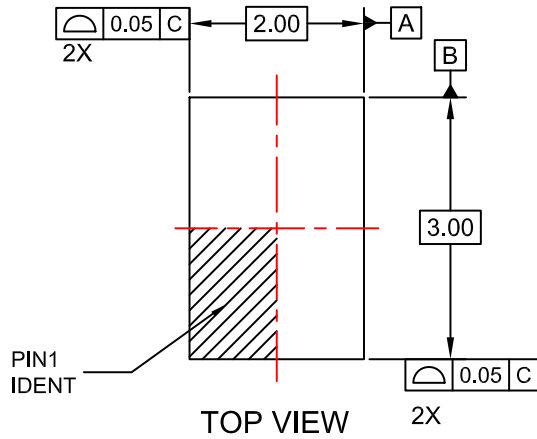


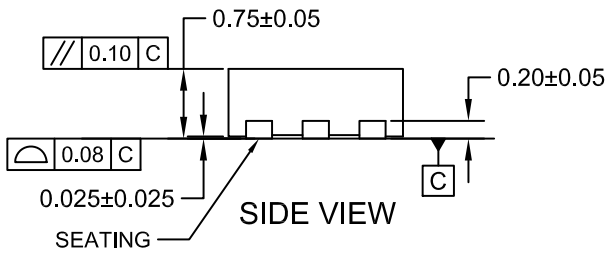
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

WDFN6 2x3, 0.65P  
CASE 511CX  
ISSUE O

DATE 31 JUL 2016

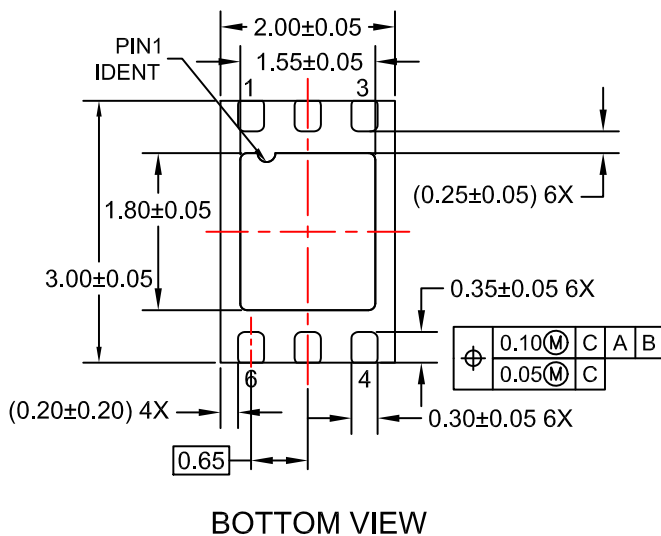


**RECOMMENDED LAND PATTERN**




**NOTES:**

- A. PACKAGE CONFORMS TO JEDEC MO-229 EXCEPT WHERE NOTED.
- B. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- C. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- D. DIMENSIONS ARE IN MILLIMETERS.
- E. REFERENCE DIMENSIONS ARE UNCONTROLLED



**BOTTOM VIEW**

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<b>DESCRIPTION:</b>	<b>WDFN6 2X3, 0.65P</b>	<b>PAGE 1 OF 1</b>

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